SOT2042-1

WLCSP9, wafer level chip scale package, 9 terminals; 0.3 mm pitch; 1.015 mm x 1.015 mm x 0.38 mm body (backside coating included)

18 November 2019

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP9
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	08-08-2019
Manufacturer package code	98ASA01498D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.995	1.015	1.035	mm
package width	0.995	1.015	1.035	mm
package height	-	0.38	0.41	mm
nominal pitch	-	0.3	-	mm
ball diameter	0.165	0.185	0.205	mm
ball height	0.115	0.13	0.145	mm
die thickness with BSP	0.225	0.25	0.275	mm
actual quantity of termination	-	9	-	

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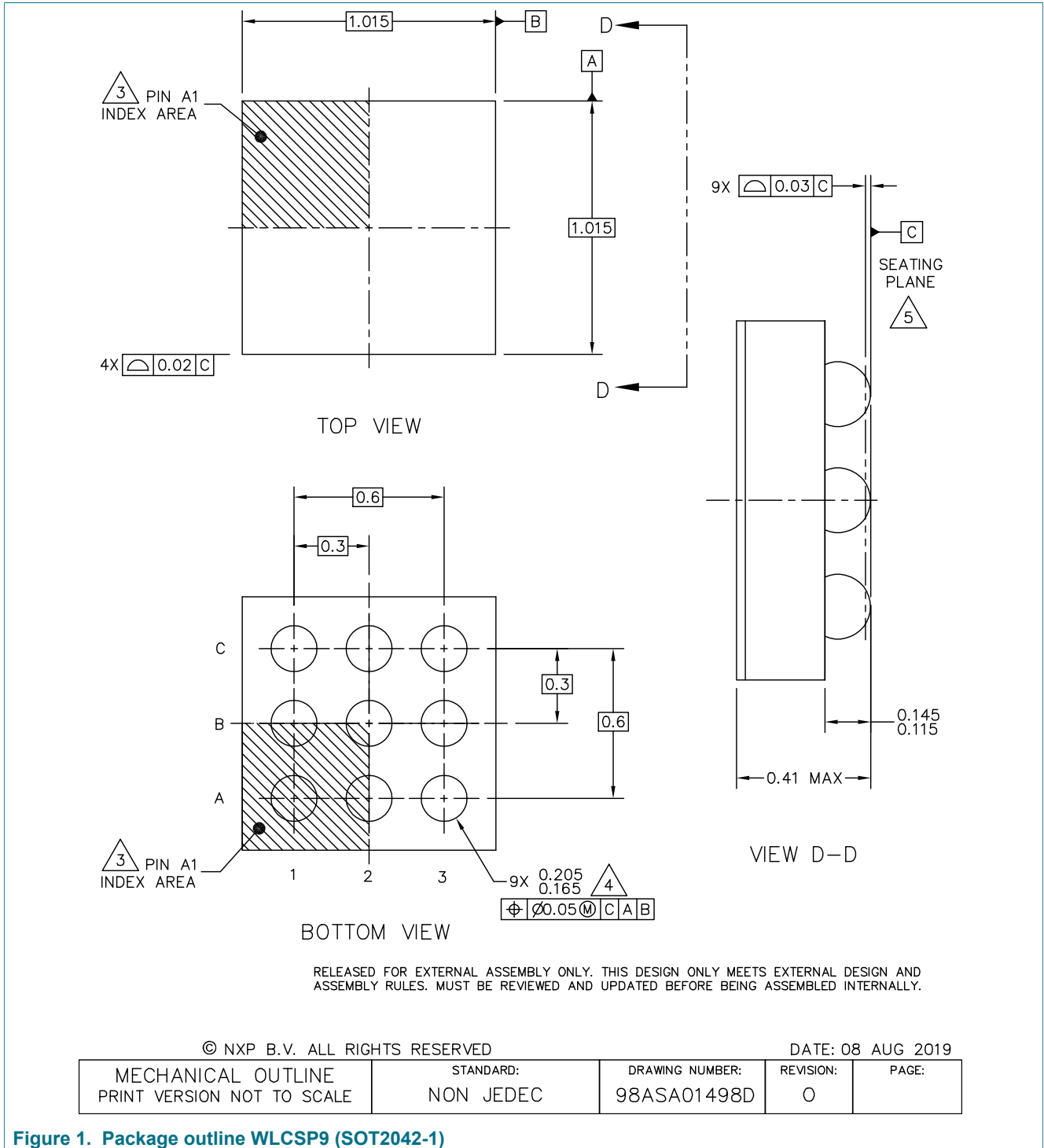
2 Package outline

TOP VIEW

BOTTOM VIEW

VIEW D—D

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DATE: 08 AUG 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01498D	REVISION: O	PAGE:

Figure 1. Package outline WLCSP9 (SOT2042-1)

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NOTES:

1.   ALL DIMENSIONS IN MILLIMETERS.

2.   DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3.   PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4.   MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.

5.   DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6.   THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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Figure 2. Package outline note WLCSP9 (SOT2042-1)

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Package information

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